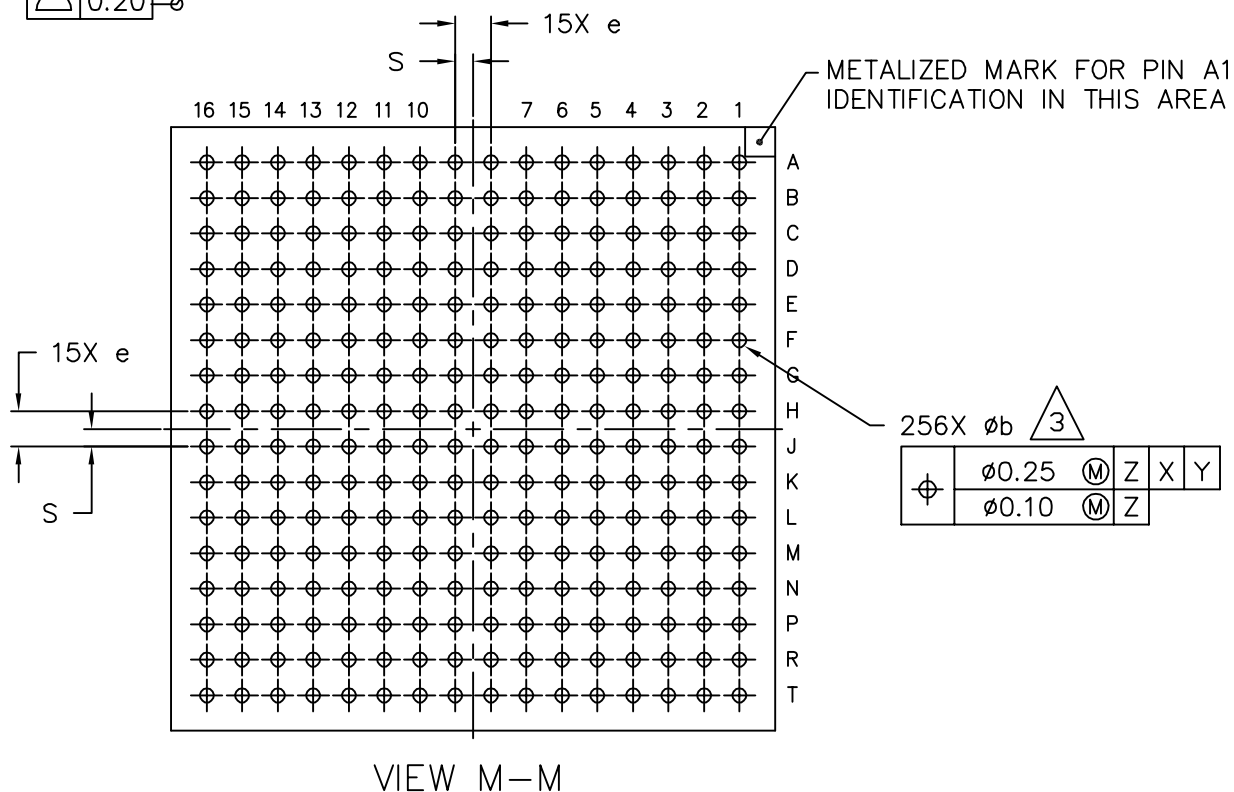
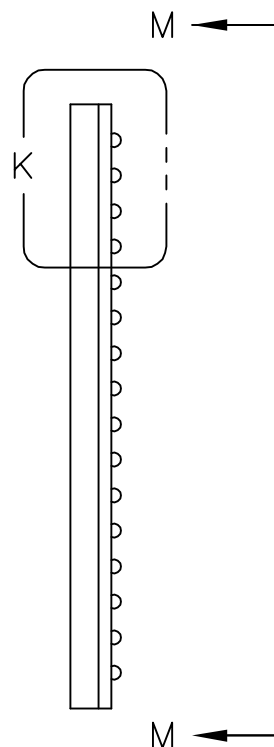
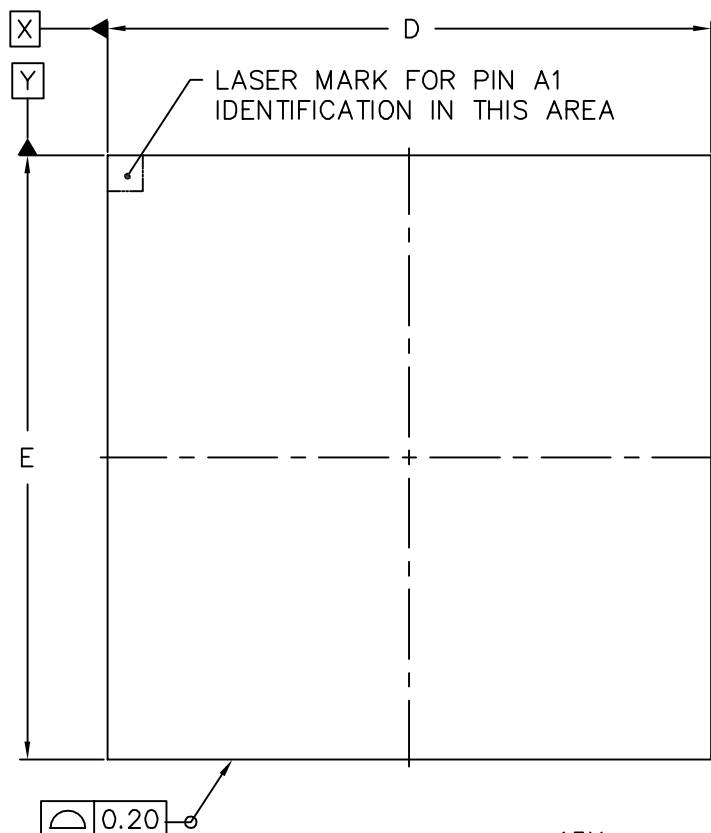




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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
256 I/O STD MAP BGA,
17 X 17 PKG, 1.00 PITCH

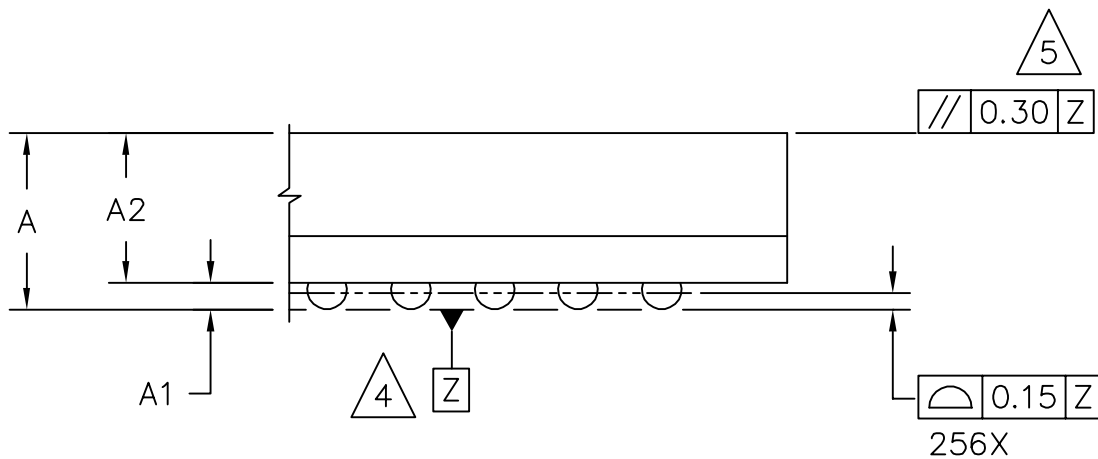
DOCUMENT NO: 98ARH98219A

REV: A

CASE NUMBER: 1216B-01

15 JUL 2005

STANDARD: NON-JEDEC



DETAIL K
ROTATED 90° CLOCKWISE

DIM	MIN	MAX	NOTES
A	1.25	1.60	1. DIMENSIONS ARE IN MILLIMETERS. 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994. 3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z. 4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS. 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
A1	0.27	0.47	
A2	1.16	REF	
b	0.40	0.60	
D	17.00	BSC	
E	17.00	BSC	
e	1.00	BSC	
S	0.50	BSC	
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